

Tamás Hurtony

List of Publications by Year in descending order

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papers

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docs citations

34
times ranked

186
citing authors

#	ARTICLE	IF	CITATIONS
1	Tin Whisker Susceptibility of SAC0307-ZnO Composite Solder Joints. , 2022, , .		0
2	Sn and Bi whisker growth from SAC0307-Mn07 and SAC0307-Bi1-Mn07 ultra-thin film layers. Vacuum, 2021, 187, 110121.	3.5	7
3	Application of ZnO Nanoparticles in Sn99Ag0.3Cu0.7-Based Composite Solder Alloys. Nanomaterials, 2021, 11, 1545.	4.1	25
4	Properties of nano-composite SACX0307-(ZnO, TiO ₂) solders. , 2021, , .		1
5	Investigation of the Mechanical Properties of Mn-Alloyed Tin-Silver-Copper Solder Solidified with Different Cooling Rates. Materials, 2020, 13, 5251.	2.9	3
6	Whisker Development from SAC0307-Mn07 Solder Alloy. , 2020, , .		0
7	Kinetics of Sn whisker growth from Sn thin-films on Cu substrate. Journal of Materials Science: Materials in Electronics, 2020, 31, 16314-16323.	2.2	9
8	Effect of Recrystallization on β to β' -Sn Allotropic Transition in 99.3Sn \pm 0.7Cu wt. % Solder Alloy Inoculated with InSb. Materials, 2020, 13, 968.	2.9	1
9	Microstructure Influence of SACX0307-TiO ₂ Composite Solder Joints on Thermal Properties of Power LED Assemblies. Materials, 2020, 13, 1563.	2.9	23
10	Wetting of Different Lead Free Solder Alloys During Vapour Phase Soldering. , 2019, , .		1
11	Early Stage Whisker Development from Sn Thin Film on Cu Substrate. , 2019, , .		0
12	Investigation of the Microstructure of Mn-doped Tin-Silver-Copper Solder Alloys Solidified with Different Cooling Rates. , 2019, , .		0
13	Characterization of Tin Pest Phenomenon in a Low Ag Content SAC Solder Alloy. , 2019, , .		1
14	Effect of Cu Substrate Roughness and Sn Layer Thickness on Whisker Development from Sn Thin-Films. Materials, 2019, 12, 3609.	2.9	13
15	Mössbauer studies of β to β' -Sn phase transition in Sn-rich solder alloys. Microelectronics Reliability, 2018, 82, 165-170.	1.7	8
16	Investigating the Fine Microstructure of Mn-doped SnAgCu Solder Alloys by Selective Electrochemical Etching. , 2018, , .		1
17	Reliability studies of InnoLot and SnBi joints soldered on DBC substrate. Soldering and Surface Mount Technology, 2018, 30, 205-212.	1.5	5
18	Whisker growth from vacuum evaporated submicron Sn thin films. Surface and Coatings Technology, 2017, 311, 216-222.	4.8	14

#	ARTICLE	IF	CITATIONS
19	Investigating current density in the lead free solder joints of surface mounted resistors with experimental approach. , 2017, , .		3
20	Characterization of the microstructure of tin-silver lead free solder. Journal of Alloys and Compounds, 2016, 672, 13-19.	5.5	16
21	Assessment of distribution of pellets in tablets by non-destructive microfocus X-ray imaging and image analysis technique. Powder Technology, 2016, 301, 228-233.	4.2	7
22	Investigating the thermomechanical properties and intermetallic layer formation of Bi micro-alloyed low-Ag content solders. Journal of Alloys and Compounds, 2015, 634, 156-162.	5.5	37
23	The correlation between the mechanical and electrochemical properties of solder joints. , 2015, , .		1
24	Investigation of surface mechanical properties of the copper-solder interface by atomic force microscopy. , 2015, , .		0
25	Electrochemical Impedance Spectroscopy as a Prospective Tool for the Characterization of the Intermetallic Microstructure of Lead Free Solder. Materials Science Forum, 2015, 812, 333-338.	0.3	4
26	Effect of current load on corrosion induced tin whisker growth from SnAgCu solder alloys. Corrosion Science, 2015, 99, 313-319.	6.6	23
27	Effects of the Cooling Rate on the Acoustic Properties of Pb-10Sn Solder. Materials Science Forum, 2012, 729, 356-360.	0.3	0
28	Investigation of the oxidation process at the copper-solder interface with atomic force microscopy. , 2012, , .		2
29	Determination of the Sn/IMC ratio in solder joints combining electrochemistry and confocal microscopy. , 2012, , .		2
30	Selective electrochemical etching for the investigation of solder joint microstructures. , 2012, , .		7
31	Investigation of intermetallic compounds (IMCs) in electrochemically stripped solder joints with SEM. Microelectronics Reliability, 2012, 52, 1138-1142.	1.7	33
32	Characterization of microstructure of lead free solder by different image processing algorithms. , 2011, , .		0
33	Metallographic analysis of laser soldered chip resistors. , 2010, , .		2
34	Microstructure Comparison of Soldered Joints Using Electrochemical Selective Etching. Materials Science Forum, 0, 729, 367-372.	0.3	7